

PCN Number:	20170616006	PCN Date:	June 20, 2017
Title:	Datasheet for TPS54620		
Customer Contact:	PCN Manager	Dept:	Quality Services
Change Type:			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design
<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Data Sheet
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Materials
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process

Notification Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details.



TPS54620

SLVS949F –MAY 2009–REVISED MAY 2017

Changes from Revision E (June 2016) to Revision F	Page
• Updated data sheet text to our latest documentation and translations standards	1
• Removed all references to the SwitcherPro™ Software Tool because it is no longer available for this part	1
• Moved storage temperature ratings to the <i>Absolute Maximum Ratings</i> table.....	5
• Changed <i>Handling Ratings</i> table to <i>ESD Ratings</i>	5
• Changed RHY package to RHL in the <i>Thermal Information</i> table	6
• Changed RGY values in the <i>Thermal Information</i> table.....	6
• Updated packages in the last bullet point of <i>Layout Guidelines</i>	34
• Added information to the last list item in <i>Layout Guidelines</i>	34

From:

7.4 Thermal Information

THERMAL METRIC ⁽¹⁾	RGY	RHY	UNIT
	14 PINS	14 PINS	
R _{thJA} Junction-to-ambient thermal resistance	36.9	43.4	°C/W
R _{thJCTop} Junction-to-case (top) thermal resistance	48.7	45.7	°C/W
R _{thJB} Junction-to-board thermal resistance	13.9	20.0	°C/W
ψ _{JT} Junction-to-top characterization parameter	0.6	0.7	°C/W
ψ _{JB} Junction-to-board characterization parameter	14.2	20.0	°C/W
R _{thJCBot} Junction-to-case (bottom) thermal resistance	3.1	2.6	°C/W

To:

6.4 Thermal Information

THERMAL METRIC ⁽¹⁾	TPS54620		UNIT
	RGY (VQFN)	RHL (VQFN)	
	14 PINS	14 PINS	
R _{thJA} Junction-to-ambient thermal resistance	40.1	40.1	°C/W
R _{thJCTop} Junction-to-case (top) thermal resistance	34.4	34.4	°C/W
R _{thJB} Junction-to-board thermal resistance	11.4	11.4	°C/W
ψ _{JT} Junction-to-top characterization parameter	0.5	0.5	°C/W
ψ _{JB} Junction-to-board characterization parameter	11.4	11.4	°C/W
R _{thJCBot} Junction-to-case (bottom) thermal resistance	1.8	1.8	°C/W

The datasheet number will be changing.

Device Family	Change From:	Change To:
TPS54620	SLVS949E	SLVS949F

These changes may be reviewed at the datasheet links provided.

<http://www.ti.com/product/TPS54620>

Reason for Change:

To accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

Changes to product identification resulting from this PCN:

None.

Product Affected:

905-5462001	TPS54620RGYR	TPS54620RGYT	TPS54620RHLLR
TPS54620RHLLT			

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com